

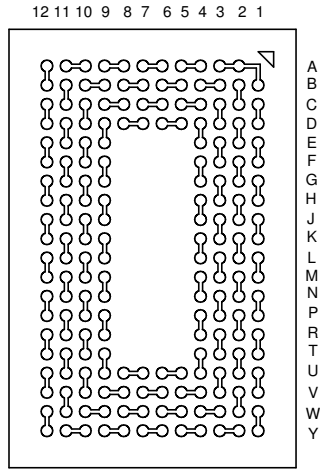
**SECTION A-A**

- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
  - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
  - 3) BALL DIAMETER (BEFORE REFLOW): 0.762mm [30 MIL].
  - 4) SOLDER MASK DEFINED PAD OPENING: 0.61mm [24 MIL].
  - 5) PAD Cu DIAMETER: 0.762mm [30 MIL].
  - 6) SUBSTRATE MATERIAL: FR4.
  - 7) DUMMY DIE SILICON >1.0MM THICK DIE STACK.
  - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
  - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

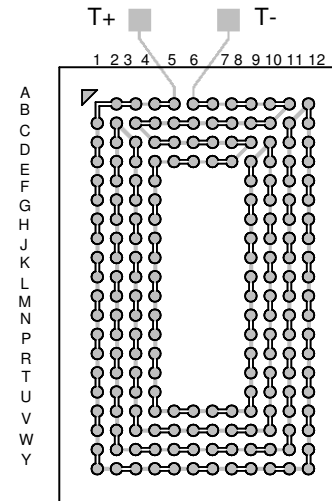
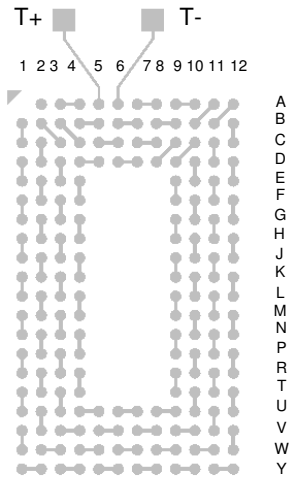
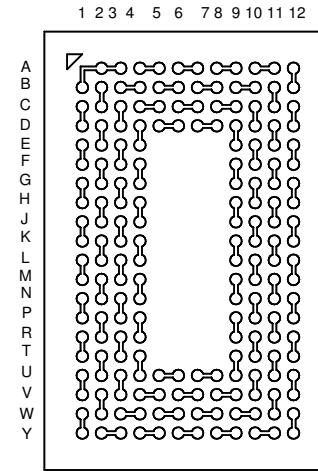
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
LBGA191T1.27C-DC1220D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
LBGA191T1.27-DC1220D	Sn63/Pb37	Sn63	NO	YES

APPROVALS		DATE	<b>TopLine</b> ®			
DRAWN	T. Au	08/09/2017	TITLE LBGA191T1.27-DC1220D DAISY CHAIN DUMMY			
ENG	M. Hart	08/09/2017				
MFG						
QA			SCALE	SIZE	DRAWING NO.	REV
CUST			5.5:1	A	526121	A
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 2

### BALL VIEW



### BOTTOM SIDE (TOP X-RAY VIEW)



### TEST VEHICLE BOARD

### AFTER MOUNTING

**Notes:**

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.762mm [30 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.254mm [10 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.61mm [24 MIL].

<b>TopLine</b> ®			
TITLE LBGA191T1.27-DC1220D DAISY CHAIN DUMMY			
SCALE 2:1	SIZE A	DRAWING NO. 526121	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	